Electronic Patent	Applicat	ion Fe	e Transm	nittal			
Application Number:							
Filing Date:							
Title of Invention:	Method of manufacturing multi-layer circuit board						
First Named Inventor:	Toshiaki Takenaka						
Filer:	Charles R. Watts/Tasha Poulain						
Attorney Docket Number:	2006-0223A						
Filed as Large Entity							
U.S. National Stage under 35 USC 371 Fil	ling Fees						
Description	Fee	e Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
National Stage Fee		1631	1	300	300		
Natl Stage Search Fee - Report provided		1642	1	400	400		
National Stage Exam - all other cases		1633	1	200	200		
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Post-Allowance-and-Post-Issurance:				
Extension-of-Time:				
Miscellaneous:			6-0 <u>1</u>	
	Tota	al in USD	(\$)	900